

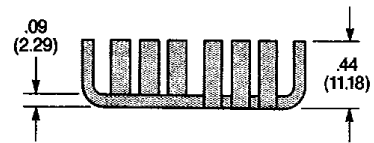
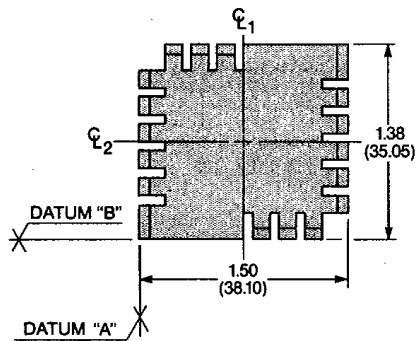
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

UP3 Series for TO-66 Outline

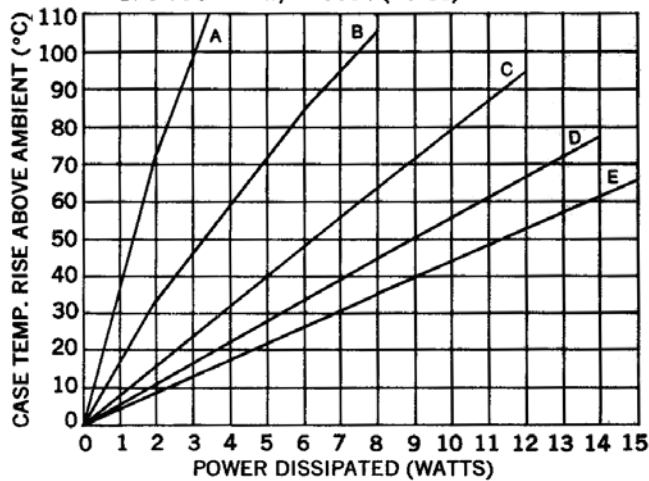
Natural Conv. ($^{\circ}\text{C}/\text{W}$): 13.6

Forced Air ($^{\circ}\text{C}/\text{W}$): 3.9

Mounting Envelope: 1.50" x 1.38" x .44"



UP3-TO66-CB w/2N3054 (TO-66) TRANSISTOR



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

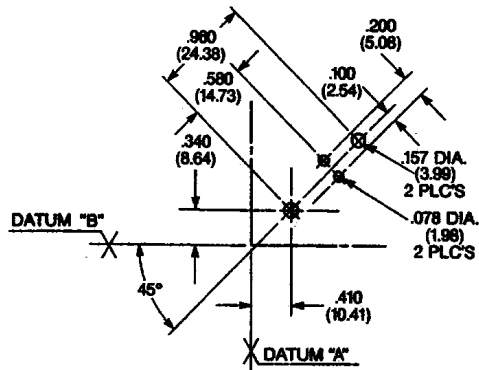
- Thermal Resistance Case to Sink is 0.6-0.7 $^{\circ}\text{C}/\text{W}$ w/Joint Compound.
- Derate 0.8 $^{\circ}\text{C}/\text{watt}$ for unplated part in natural convection only.
- Derate 0.8 $^{\circ}\text{C}/\text{watt}$ for Insulube[®] part in natural convection only.

Ordering Information

CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
UP3-T066-U	UP3-T066-CB	UP3-T066-B	T0-66	14	10.5

HOLE PATTERNS

14. Hole pattern no. 138 accommodates T0-66s. Available in UP3 series heat dissipators only.



CTS IERC, Heat Sinks and Thermal Management Solutions

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